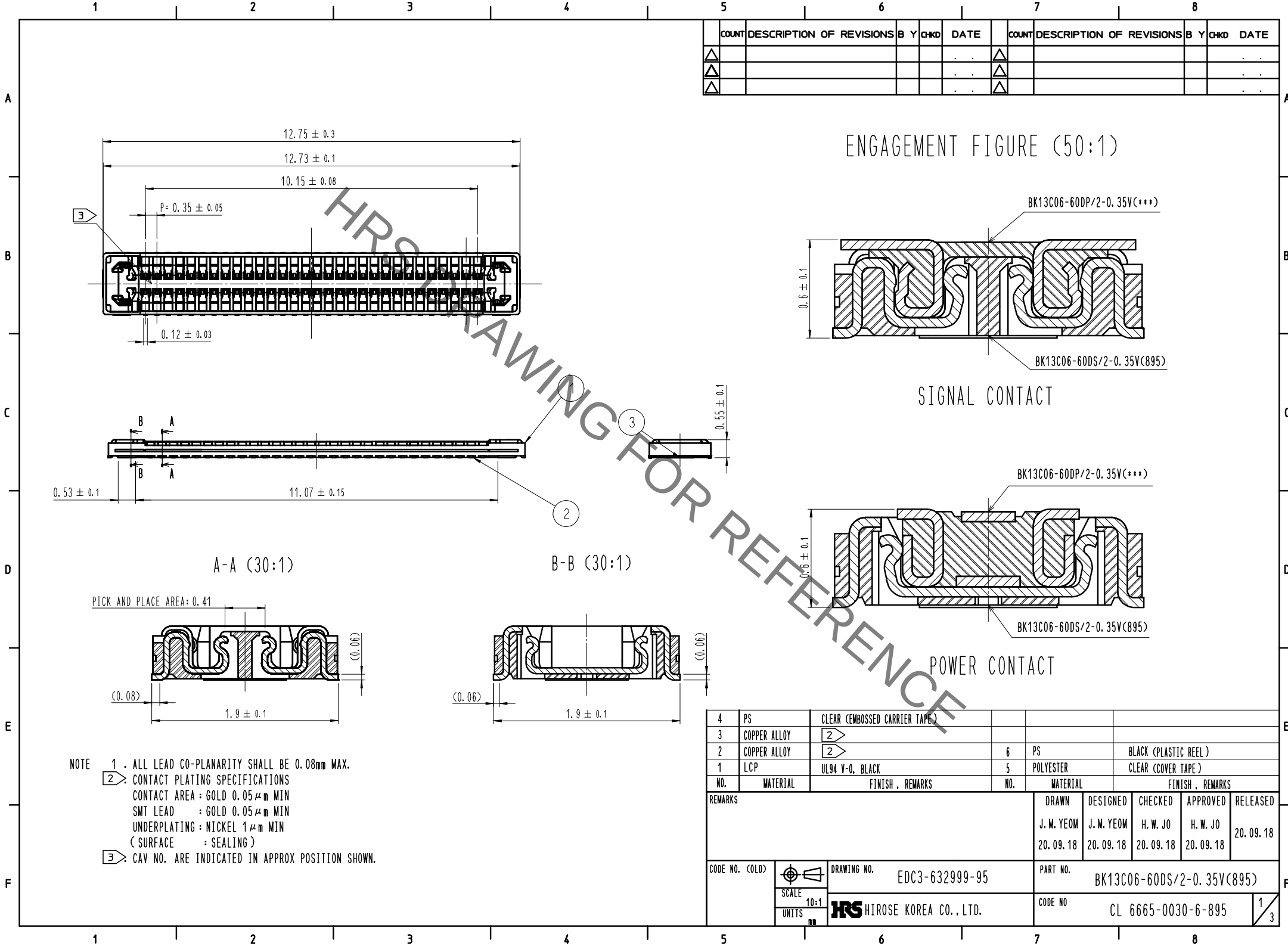




The technical drawing illustrates the dimensions and temperature profile for a reflow soldering process. The top left shows a cross-section of the assembly with various dimensions: 12.995 ± 0.02, 10.15 ± 0.02, 0.215 ± 0.02, 0.18 ± 0.02, 0.15 ± 0.02, 1.04, 1.63, and 0.05. The insulation area is indicated. The bottom left shows a side view with dimensions 12.995 ± 0.02, 10.15 ± 0.02, and 0.215 ± 0.01. The right side shows a temperature profile graph with Temperature (°C) on the Y-axis (0 to 200) and Time on the X-axis. The profile shows a pre-heat phase (60 seconds) and a reflow phase (90-120 seconds) reaching 150°C.

TEMPERATURE PROFILE

TEMPERATURE (°C)

180

150

150°C

100

25

0

(60 SECONDS)

90-120 SEC

PRE-HEAT

REWORK METHOD : N

NUMBER OF REFLOW

1) REFLOW TIME

DURATION ABOVE

(PEAK TEMPERATURE)

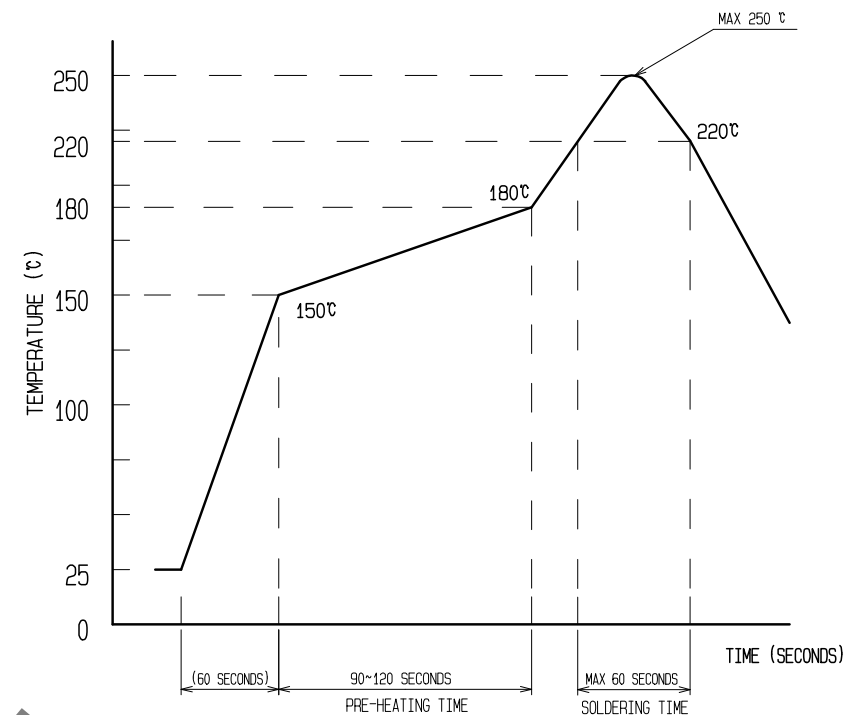
2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE

PRE-HEAT TEMPERATURE

PRE-HEAT TIME

4. THIS TEMPERATURE PROFILE IS FOR REFERENCE



REFLOW METHOD : N₂ REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC. MAX.
(PEAK TEMPERATURE : 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

4. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

5. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO. EDC3-632999-95		PART NO. BK13C06-60DS/2-0.35V(895)	
	SCALE 10:1 UNITS 		CODE NO CL 6665-0030-6-895	
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